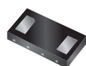
Material Composition Specification
DFN123F Case

Top View


Bottom View

Device average mass . . . . 14.25 mg
Fluctuation margin . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	2.105%	0.300	Si	7440-21-3	2.11%	0.300	21,053
bond wire	gold	0.154%	0.022	Au	7440-57-5	0.15%	0.022	1,544
leadframe	copper alloy	25.916%	3.693	Cu	7440-50-8	25.71%	3.664	257,123
				Si	7440-21-3	0.18%	0.025	1,754
				Mg	7439-95-4	0.03%	0.004	281
	plating	0.765%	0.109	Ni	7440-02-0	0.73%	0.104	7,298
				Pd	7440-05-3	0.03%	0.004	281
				Au	7440-57-5	0.01%	0.001	70
die attach	silver epoxy	0.519%	0.074	Ag	7440-22-4	0.36%	0.051	3,579
				epoxy resin	Proprietary	0.16%	0.023	1,614
encapsulation	EMC GREEN	70.540%	10.052	silica (fused)	60676-86-0	68.94%	9.824	689,404
				epoxy resin	29690-82-2	0.71%	0.101	7,088
				phenol resin	9003-35-4	0.71%	0.101	7,088
				carbon black	1333-86-4	0.18%	0.025	1,754
				metal hydroxide	1309-42-8	0.01%	0.001	70

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.